

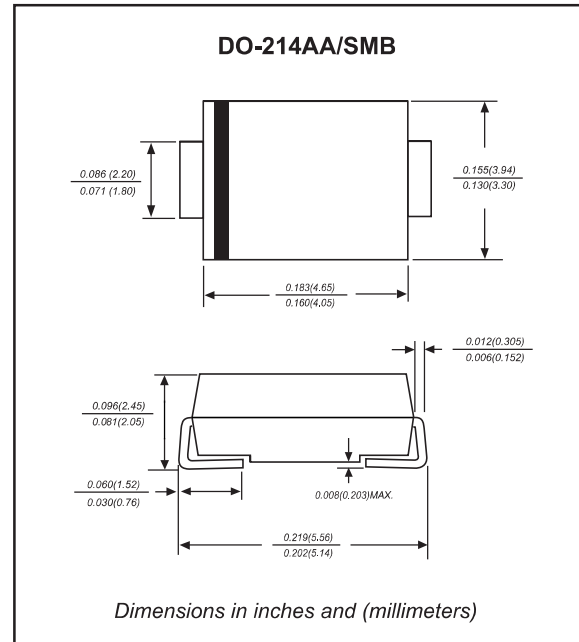
Features

- 600W peak pulse power capability with a 10/1000 μ s waveform, repetition rate (duty cycle): 0.01%.
- Low profile surface mounted application in order to optimize board space.
- Excellent clamping capability.
- Low incremental surge resistance.
- Fast response time from 0V to VBR, typically less than 1 ps for uni-directional & 5 ns for bi-directional types.
- Glass passivated chip junction.
- Lead-free parts meet RoHS requirements.
- Compliant to Halogen-free

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA / SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Peak power dissipation	with a 10/1000 μ s waveform, Note 1 & Fig. 1	P_{PPM}			600	W
Peak pulse current	with a 10/1000 μ s waveform	I_{PPM}	58.1			A
Steady state power dissipation	at $T_L=75^\circ\text{C}$ lead length 0.375" (9.5 mm)	$P_{M(AV)}$			5.0	W
Peak forward surge current	8.3ms single half sine-wave superimposed on rated load (jedec method), note 2	I_{FSM}			100	A
Maximum instantaneous forward voltage	for uni-directional types only, at 50A, see note 3	V_F			3.5/5.0	V
Operating junction temperature range		T_J	-55		+150	$^\circ\text{C}$
Storage temperature range		T_{STG}	-55		+150	$^\circ\text{C}$

Note 1. Non-repetitive current pulse, per Fig. 3 and derated above $T_A=25^\circ\text{C}$ per Fig. 2

2. Measured on 8.3 ms single half sine-wave or equivalent square wave, duty cycle=4 pulses per minute maximum

3. $V_F < 3.5\text{V}$. for devices of $V_{BR} < 200\text{V}$, and $V_F < 5.0\text{V}$. for devices of $V_{BR} > 201\text{V}$

Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Type Number		Reverse Stand-Off Voltage	Breakdown Voltage Min. @ I_T	Breakdown Voltage Max. @ I_T	Test Current	Maximum Clamping Voltage @ I_{PP}	Peak Pulse Current	Reverse Leakage @ V_{RMW}
(Uni)	(Bi)	$V_{RMW}(V)$	$V_{BR MIN}(V)$	$V_{BR MAX}(V)$	$I_T (mA)$	$V_C(V)$	$I_{PP}(A)$	$I_R(\mu A)$
SMBJ6.8A	SMBJ6.8CA	5.80	6.45	7.14	10.0	10.5	58.1	1000.0

※ For Bi-directional type having VRWM of 10 Volts and less, the IR limit is double

Rating and characteristic curves

Fig.1 - PEALK PULSE POWER RATING CURVE

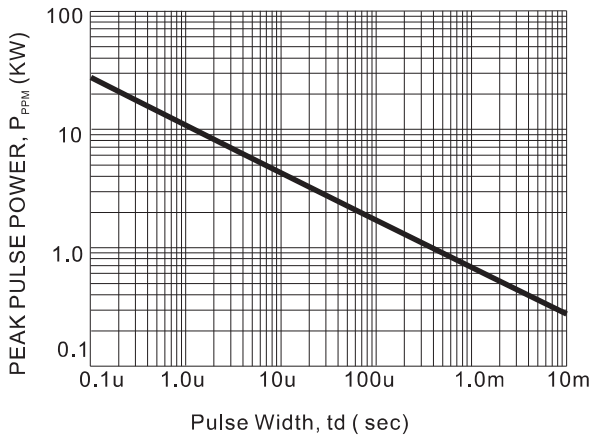


Fig.2 - PULSE DERATING CURVE

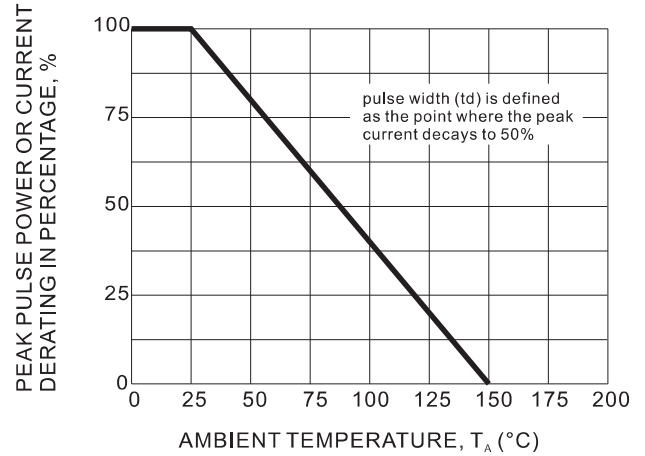


Fig.3 - PULSE WAVEFORM

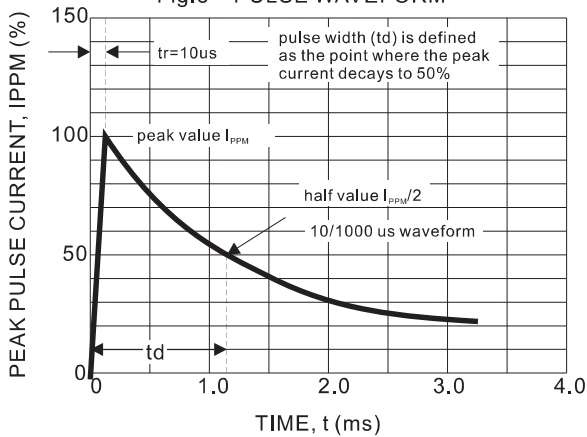


Fig.4 - TYPICAL JUNCTION CAPACITANCE

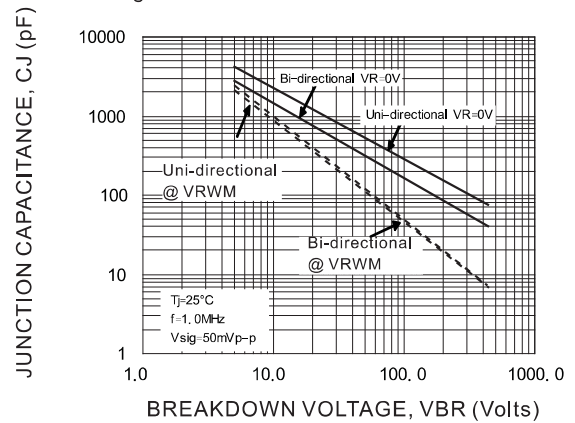


Fig.5 - STEADY STATE POWER DERATING CURVE

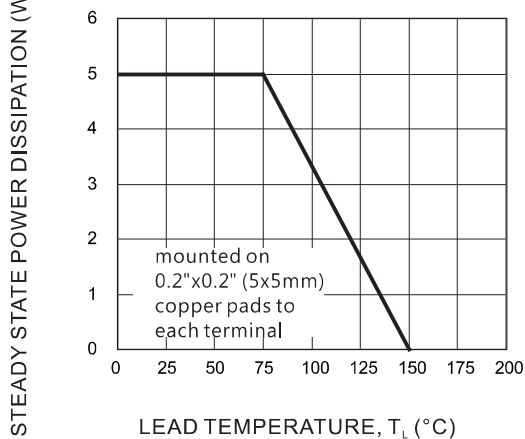
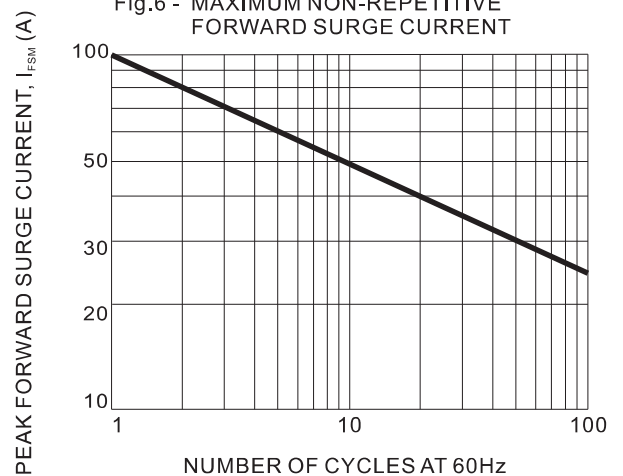

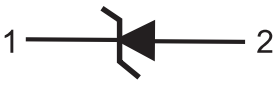




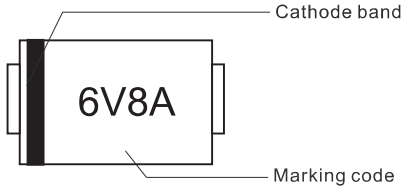
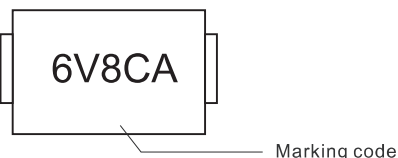
Fig.6 - MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



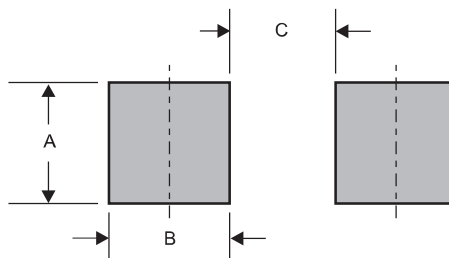
Pinning information

Pin	Simplified outline	Symbol
Uni-Directional Pin1 cathode Pin2 anode		
Bi-Directional		

Marking

Type number	Example
Uni-Directional	
Bi-Directional	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.078 (2.00)	0.059 (1.50)	0.110 (2.80)